



DOCKET NO: 268844US0PCT

"RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 1765"

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

HIROSHI SHIHO, ET AL.

: EXAMINER: CHEN, KIN CHAN

SERIAL NO: 10/529,742

:

FILED: JANUARY 6, 2006

: GROUP ART UNIT: 1765

FOR: POLISHING PAD FOR
SEMICONDUCTOR WAFER AND
LAMINATED BODY FOR POLISHING OF
SEMICONDUCTOR WAFER EQUIPPED
WITH THE SAME AS WELL AS
METHOD FOR POLISHING OF
SEMICONDUCTOR WAFER

Reconsideration only

8/15/07

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

kcc

SIR:

Responsive to the Office Action of June 8, 2007, Applicants request reconsideration
in view of the following remarks.

Remarks begin on page 2 of this paper.